ON Semiconductor

Final Product/Process Change Notification

Document # : FPCN16790XHV
Issue Date: 14 October 2015

Title of Change:	Final PCN for wafer fab transfer from Gifu in Japan to Niigata in Japan (Group HV).
Proposed first ship date:	21 January 2016
Contact information:	Contact your local ON Semiconductor Sales Office or <Yasuhiro.Igarashi@onsemi.com>
Samples:	Contact your local ON Semiconductor Sales Office
Additional Reliability Data:	Contact your local ON Semiconductor Sales Office or <Kazutoshi.Kitazume@onsemi.com>.
Type of notification:	This is a Final Product/Process Change Notification (FPCN) sent to customers. FPCNs are issued 90 days prior to implementation of the change. ON Semiconductor will consider this change accepted, unless an inquiry is made in writing within 30 days of delivery of this notice. To do so, contact <PCN.Support@onsemi.com>.
Change Part Identification:	Affected products will be identified with date code.
Change category:	☒ Wafer Fab Change ☐ Assembly Change ☐ Test Change ☐ Other ________________

Change Sub-Category(s):
☒ Manufacturing Site Change/Addition
☐ Manufacturing Process Change
☐ Material Change
☐ Product specific change
☐ Datasheet/Product Doc change
☐ Shipping/Packaging/Marking
☐ Other: ________________________

Sites Affected:
☐ All site(s)
☐ not applicable
☒ ON Semiconductor site(s) :
ON Niigata, Japan
ON Gifu, Japan
☐ External Foundry/Subcon site(s)

Description and Purpose:
This is a Final Process Change Notification to announce about the transfer of products from ON Semiconductor wafer fabrication sites located in Gifu Japan to the wafer fabrication ON Semiconductor Niigata Co., Ltd.(OSNC). OSNC is located in Niigata, Japan, obtained ISO9001 certification.

The product design and electrical specifications will remain identical. A full electrical characterization over the temperature range will be performed for each product to check the device functionality and electrical specifications.

Reliability Data Summary:

Test	Specification	Condition	Interval	Results
HTRB	JESD22-A108	Ta=150°C, 100% max rated VDSS	1008 hrs	0/22
HTGB	JESD22-A108	Ta=150°C, 100% max rated Vgss	1008 hrs	0/22
HTSL	JESD22-A103	Ta=150°C	1008 hrs	0/22
IOL	MIL-STD-750 (M1037) AEC-Q101	delta Tj=100°C	8572 cyc	0/22
TC	JESD22-A104	Ta= -55°C to +150°C	200 cyc	0/22
H^{3}TRB	JESD22-A110	85°C, 85% RH, 80% max rated VDSS	1008 hrs	0/22
AC	JESD22-A118	121°C, 100% RH, 2.03×105Pa, unbiased	96 hrs	0/22
PC	J-STD-020 JESD-A113	MSL 1 @ 260°C		
RSH	JESD22- B106	Ta = 265C, 10 sec		0/22
SD	JSTD002	Ta = 245C, 10 sec		0/22

Electrical Characteristic Summary:

There is no change in the electrical performance. Datasheet specifications remain unchanged.

List of affected Standard Parts:

Part Number	Qualification Vehicle
2SK3703-1E	SMP4003-DL-1E
2SK3816-DL-1E	SMP4003-DL-1E